

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	269	(438/67).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/06/19 10:42
L2	175	(438/68).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/06/19 10:42
L3	1276	(438/107).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/06/19 10:42
L4	1589	(438/108).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/06/19 10:42
L5	1043	(438/113).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2006/06/19 10:43
L6	276	(((semiconductor adj package) or (semiconductor adj wafer))) and solder and (resin or underfill or encapsulant) and (hardening or harden or curing or cure) and (severing or severe or cut or cutting or separat\$5) and (heat adj treat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/06/19 10:43